

IN THE SPECIFICATION:

After the title, please insert the following:

--This application is a divisional of and claims priority to co-pending United States Patent Application Serial No. 10/090,094 filed on March 4, 2002, ^{Pat. 6,798,074} entitled "Method of Attaching a Die to a Substrate," naming Man Hon Cheng, Wai Wong Chow, and Wai Keung Ho as inventors, and having as assignee the assignee of the present invention, and which is incorporated herein by reference.--